

Title (en)
DIELECTRIC INK COMPOSITION

Title (de)
DIELEKTRISCHE TINTENZUSAMMENSETZUNG

Title (fr)
COMPOSITION D'ENCRE DIÉLECTRIQUE

Publication
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Application
EP 18801698 A 20180514

Priority
• US 201762506095 P 20170515
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Abstract (en)
[origin: WO2018213161A1] The present invention relates to flexible and stretchable UV and thermally curable dielectric ink compositions that can be thermo or vacuum formed. The flexible ink can form a stretchable dielectric coating having excellent adhesion. The dielectric ink compositions can be applied on a circuit board, such as a paper-phenolic resin board, plastic board (PMMA, PET or the like) or a glass-epoxy resin board, by screen printing or the like, followed by heat/UV curing. The compositions are suitable for use in applications such as a capacitive touch, in-mold forming, creating cross over insulation layers, and manufacturing electronic circuitry and devices.

IPC 8 full level
C09D 11/101 (2014.01)

CPC (source: EP US)
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C-Set (source: US)
C09D 11/10 + C09D 11/52

Citation (search report)
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• [X1] US 2014151606 A1 20140605 - LOWENTHAL MARK DAVID [US], et al
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• See also references of WO 2018213161A1

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
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